In a production environment where a fast solution to a problem is essential, internal material defects, complicated assemblies and hidden geometries can all be too complex and time consuming for manufacturers’ inhouse inspection capabilities. Traditional destructive methods of potting and slicing parts to analyze internal structures are often ineffective and add considerable time and expense to your validation process.

Nikon Metrology X-ray & CT inspection services offer the right capabilities to explore prototypes, samples or series for internal deficiencies. It is fast, non-destructive and provides insightful 3D analysis. And at the Nikon Metrology contract inspection department, the CT experts go further; they not only provide a detailed 3D scan, but also interpret the CT results to help you find the cause of issues.

**Nikon Metrology X-ray & CT inspection services help you to focus on what matters to you**

**Delivering high quality products in the shortest time possible**

**What Nikon Metrology CT technology offers**
- High power microfocus sources for highest resolution
- Unique high-flux rotating targets for fast scan times
- Wide range of systems for scanning small parts to large assemblies
- Inspection of a wide variety of materials: metals, alloys, plastics, ceramics, composites, bone and tissue
- Non-destructive analysis preserves (expensive) samples
- Material/defect analysis, porosity analysis, composite fiber analysis, part-to-CAD comparison, GD&T, STL creation, BGA analysis and 2D radiography
- Accurate measurement of internal and external dimensions

**Benefits of Nikon Metrology X-ray & CT services**
- Over 30 years expertise in X-ray CT
- Fully equipped laboratories featuring 160-450 kV microCT systems
- In case your inhouse CT capacity is limited or not adequate for specific projects, rely on Nikon CT service capability
- Small one-off projects to large batch inspections
- Customized reporting and analysis to meet your requirements
- Controlled project costs instead of investment in own CT facilities
- Short turnaround times
- Nearby services throughout Europe

**Application examples**
- Connectivity issues in electrical components
- Measuring small internal geometries
- Internal voids or cooling channels in AM parts
- Assembly verification of one-off or critical use components
- Material analysis (foam)
- PCB(A): BGA voids, broken bonds, wire sweep etc